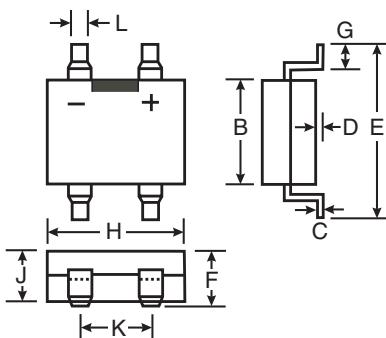


## Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automatic Assembly
- Miniature Package Saves Space on PC Boards
- **Lead Free Finish, RoHS Compliant (Note 4)**

## Mechanical Data

- Case: MiniDIP
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Terminals: Finish — Bright Tin. Plated Leads, Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Marking: Type Number
- Weight: 0.125 grams (approx.)



MiniDIP		
Dim	Min	Max
B	3.6	4.0
C	0.15	0.35
D	—	0.20
E	—	7.0
F	—	3.00
G	0.70	1.10
H	4.5	4.9
J	2.3	2.7
K	2.3	2.7
L	0.50	0.80

All Dimensions in mm

## Maximum Ratings and Electrical Characteristics

@  $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	RH02	RH04	RH06	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RMM}$ $V_{RWM}$ $V_{DC}$	200	400	600	V
RMS Reverse Voltage	$V_{RMS}$	140	280	420	V
Average Forward Rectified Current (Note 1) $T_A = @ 40^\circ\text{C}$	$I_O$		0.5		A
Non-Repetitive Peak Forward Surge Current, 8.3 ms Single half-sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$		30		A
Instantaneous Voltage Drop @ 0.4A (per element)	$V_F$		1.15		V
Peak Reverse Current at Rated DC Blocking Voltage (per element) @ $T_A = 25^\circ\text{C}$ @ $T_A = 125^\circ\text{C}$	$I_R$		5.0 100		$\mu\text{A}$
Maximum Reverse Recovery Time (Note 3)	$t_{rr}$	150	250		ns
Typical Junction Capacitance (per element) (Note 2)	$C_j$		13.0		pF
Typical Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$		85		K/W
Operating and Storage Temperature Range	$T_j, T_{STG}$		-55 to +150		$^\circ\text{C}$

Notes:

1. Mounted on Glass Epoxy PC Board.
2. Measured at 1.0 MHz and Applied Reverse Voltage of 4.0 V.
3.  $t_{rr}$  test conditions:  $I_F = 0.5\text{A}$ ,  $I_R = 1.0\text{A}$ ,  $I_{rr} = 0.25\text{A}$ .
4. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.

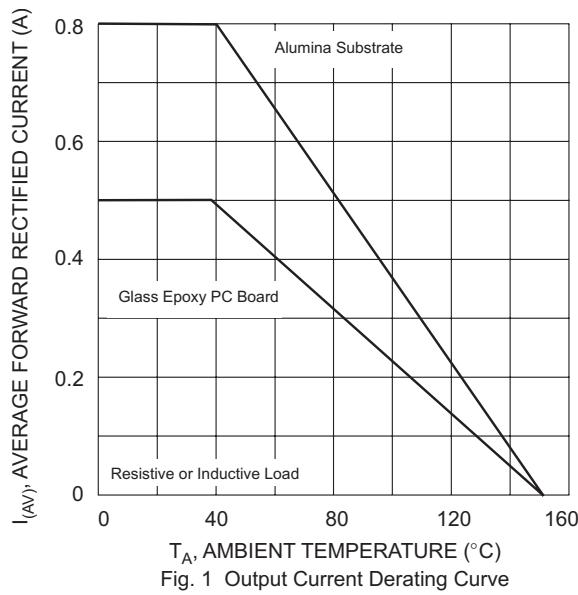


Fig. 1 Output Current Derating Curve

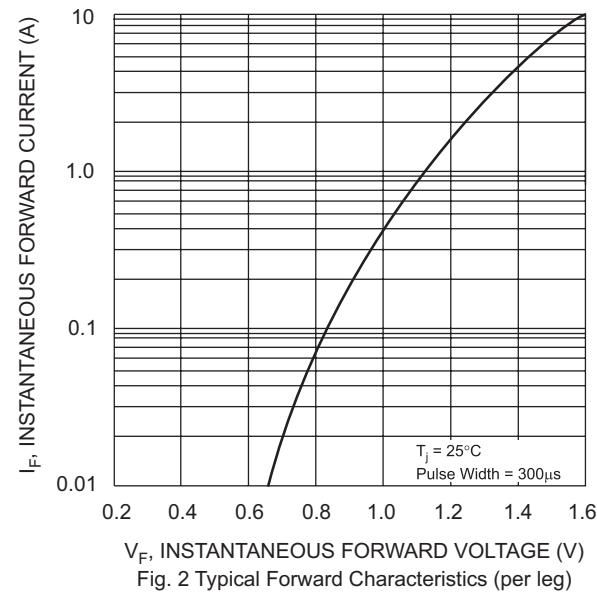


Fig. 2 Typical Forward Characteristics (per leg)

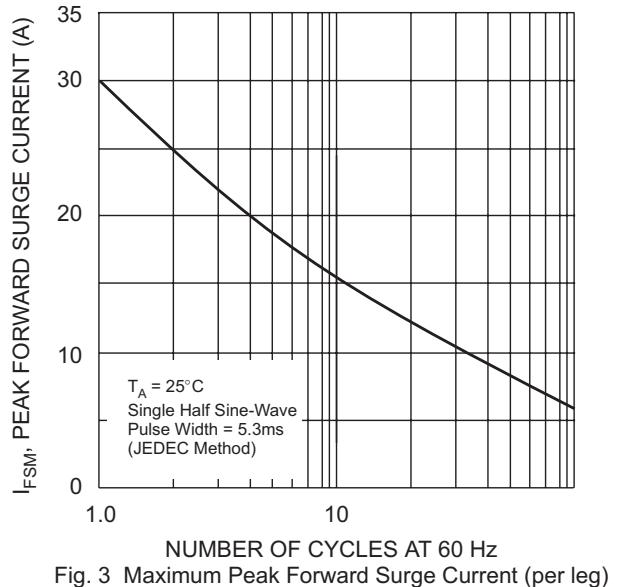


Fig. 3 Maximum Peak Forward Surge Current (per leg)

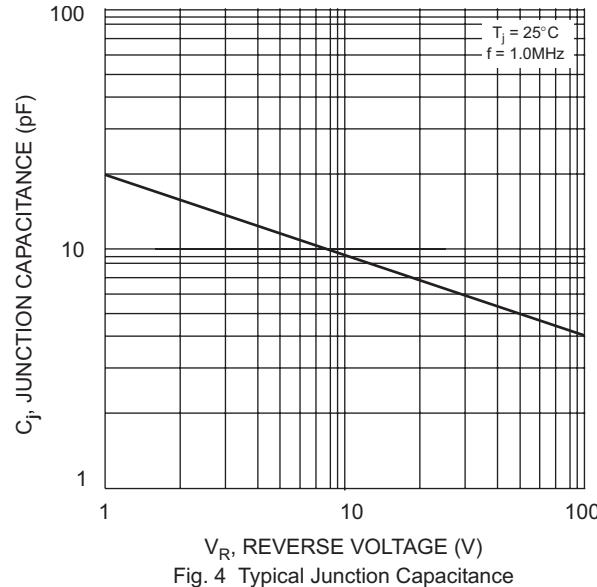


Fig. 4 Typical Junction Capacitance

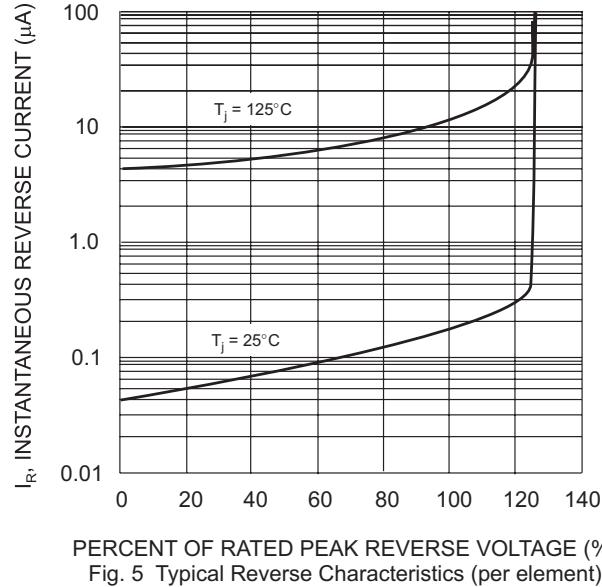


Fig. 5 Typical Reverse Characteristics (per element)

**Ordering Information** (Note 5)

Device	Packaging	Shipping
RH0x-T	MiniDIP	3000/Tape & Reel

Notes: 5. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.